Contact Name   Title - Contact   Phone - Contact*   Email - Contact*	(0	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID  Unique ID Authority  Response Date*  2023-06-08  Contact Name Contact Name Contact Env-Stewards Contac						e *						als and Mf	fg Information	on		
Semil   Contact Name   Title - Contact   Phone - Contact   Phone - Contact   Phone - Contact   Product Env-Stewards   Product Enviro Compliance   NA   Product Env-Stewards @ onsemi.com   Phone - Representative   Phone - Representative   Phone - Representative   Phone - Representative   Product Enviro Compliance   NA   Product Env-Stewards @ onsemi.com   Requester Item Number   Mfr Item Number   Mfr Item Name   Effective Date   Version   Manufacturing Site   Weight   UOM   Product Enviro Compliance   UM2576TV-3.3G   ANA 3.3V 3A PWR SW REG   2023-06-08   MY1   1960.42   mg   Insufacturing Process Information   Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles   Matte Tin (Sn) - annealed   CU Alloy   NA   0   C   30   seconds   3   Seconds   CU Alloy   C   CO Alloy   C   C   C   CO Alloy   C   C   C   C   C   C   C   C   C	lier Informati	ion														
Product Name   Product Enviro Compliance   Phone - Contact*   Product Enviro Compliance   Phone - Representative*   Product Enviro Compliance   Phone - Representative*   Product Enviro Compliance   Phone - Representative*   Product Enviro Compliance   Product Enviro Compliance   Phone - Representative*   Product Enviro Compliance   Product Enviro Stewards © onsemi.com	Company name*				Company unique ID			Unique ID Authority					Response Date*			
Product Env-Stewards Uthorized Representative* Title - Representative Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards © onsemi.com NA Product Env-Stewards © onsemi.com NA Product Env-Stewards © onsemi.com NA Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site NA NA NA 3.3V 3A PWR SW REG NA NA NA NA 3.3V 3A PWR SW REG NA													2023-06-	-08		
Title - Representative* Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Meight* UOM M71 1960.42 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed CU Alloy NA Product-Env-Stewards©onsemi.com Manufacturing Site Weight* UOM M71 1960.42 mg  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds 3	t Name			Title - Contact			]	Phone - Contact*					Email - Contact*			
Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  LM2576TV-3.3G ANA 3.3V 3A PWR SW REG 2023-06-08 MY1 1960.42 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 Seconds 3	ct-Env-Stewards	5		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*				
LM2576TV-3.3G ANA 3.3V 3A PWR SW REG 2023-06-08 MY1 1960.42 mg    Institution   Instit	Product-Env-Stewards				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles   Matte Tin (Sn) - annealed   CU Alloy   NA   0   C   30   seconds   3	Requester Ite	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date	Versi	on	Manufacturing Site		V	Weight*	UOM	Unit Type
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Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3				. 10	.,,	( GTTD .020 ) (G	I D		D 1	T.	] A		T		CD C	1
Figure 1m (b) dimensed to the property of the							L Rating				me at Peak			er of Reflow Cyc	cles	
omments	•	on) - annealed	C	U Alloy		NA		U		IC.	30		second	as 5		
	ents															
or more information regarding material composition please refer to page 3			•.•	•												

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated diphenyls of an applicable quantity limit, please indication in the graph of an applicable quantity limit, please indications. Supplier acknowledges that Company will we relied on information provided by others in a minimum and the Supplier agrees that, at a minimum and the Supplier enter into a written agreem source of the Supplier's liability and the Company of the Supplier's liability and the Supplier's liability and the Supplier's liability and the Company of the Supplier's liability and the Supplier's liabi	J 2011/65/EU and implemented by the laws of the Eyl ethers (each a "RoHS restricted substance") in exate below which, if any, RoHS exemption you belie les in this form using appropriate methods to ensure rely on this certification in determining the complian completing this form, and that Supplier may not ha, its suppliers have provided certifications regarding tent with respect to the identified part, the terms and impany's remedies for issues that arise regarding info cable to such part shall apply.	cess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- unce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certifications conditions of that agreement, including any warr	ove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.83	mg	A	Lead (Pb)	7439-92-1	7a	78.6885	mg
			Supplier	Tin (Sn)	7440-31-5		4.1415	mg
Lead Frame	1297.64	mg	Supplier	Copper (Cu)	7440-50-8		1297.64	mg
Mold Compound-Black	543.9	mg		Epoxy resin	proprietary data		38.073	mg
			Supplier	Phenolic Resin	Proprietary Data		38.073	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.585	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.4495	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg